

<http://www.polytronic2005.org>

Polytronic 2005, the 5<sup>th</sup> International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics, will be held on **October 23-26, 2005** in Wroclaw, Poland.

The conference provides a unique opportunity for the meeting of polymer developers with polymer users from the electronics industries. Research paper presentations will cover all aspects of adhesives and polymers in microelectronics and photonics, including new polymers, organic devices, polymers in packaging, and adhesive applications.

Polytronic 2005 will be the fifth in the Conference series, begun in 2001 as an amalgamation of the previously successful series of IEEE Conferences on adhesives and polymers: Polymeric Materials for Microelectronic & Photonic Applications (POLY), Adhesives in Electronics, and Polymeric Electronics Packaging (PEP).

### The topics that will be covered include:

**Materials:** Thermosetting/thermoplastic systems; inorganic adhesives; composites; filler materials; isotropic conductive adhesives; anisotropic conductive adhesives; underfill compounds; pastes and films; heat seal connectors; thermally conductive adhesives; polymers with adapted refractive index; photosensitive polymers; high temperature materials; PCB materials, polymer thick and thin films, low and high dielectric materials.

**Processing and Manufacturing:** Advanced packaging; lamination; printing; dispensing; spraying; transfer techniques; underfilling; potting; adhesion improvement; curing; equipment; statistical process control; economic analyses.

**Design and CAD:** Design, modeling, simulation, CAD of compounds and processes; thermo-mechanical behavior.

**Reliability and Testing:** Degradation mechanisms; adhesion; hermeticity; accelerated testing; humidity and environmental sensitivities; non-destructive testing methods; stress behavior.

**Functional Polymers for Microelectronics:** Conductivity of polymers; electronic transport; self-assembly; photoactivity; polymeric materials for molecular electronics.

**Applications:** Polymer electronic devices; polymer optical fibers; polymer wave guides; organic displays; polymer batteries; e-paper; flexible electronics.

**Environmental Issues:** Ecology and toxicology; life cycle analyses.

### Submission of abstracts (31 May 2005)

Abstract should include the following:

- **ABSTRACT TITLE**
- **AUTHOR LISTING** (principal author first): First (given) name, Last (family) name, and affiliations, mailing address, telephone, fax and e-mail address.
- **PRESENTATION:** Indicate which Session Topic your paper matches and whether you prefer to do an Oral Presentation or a Poster Presentation. Placement is at the Chair's discretion.
- **ABSTRACT TEXT:** Not less than 250 words; preferably 1500 words.
- **KEY WORDS** List a maximum of five key words.
- **BRIEF BIOGRAPHY** (of principal author) Approximately 50 words.

**Note: Electronic submission only.** Submit abstracts to: [papers@polytronic2005.org](mailto:papers@polytronic2005.org). Detailed information about the submission process for final papers will be posted later on the official conference web site (<http://www.polytronic2005.org>).

- **Notification of acceptance: 15 June 2005**
- **Final papers due: 05 September 2005**